



For Immediate Release

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SyChip Introduces High-Speed WLAN SDIO Driver *Solution Enables True Broadband Connectivity In Handheld Devices*

PLANO, TX, (October 23, 2007) — SyChip, Inc., a leader in Radio Frequency Chip Scale Modules (CSM) and a subsidiary of Murata Manufacturing Co., Ltd., today announced the launch of its High-Speed Secure Digital Input/Output (HS-SDIO) driver for Wi-Fi enabled mobile devices. This HS-SDIO solution allows consumers using Microsoft® Windows CE devices to realize effective data throughput of up to 16Mbps, thus enabling true high speed Internet access on a mobile handset.

SyChip's HS-SDIO driver doubles the wireless LAN (WLAN) throughput in current Windows CE devices. Since SDIO is the most popular interface used in mobile embedded WLAN today, this driver, together with the company's WLAN module, provides designers a high performance wireless solution that can be quickly integrated into handheld device. The HS-SDIO driver is initially available on the Marvell® PXA270 and PXA300 family of processors, but it can also support other application processor platforms.

"The goal is to provide our customers with industry-leading plug-and-play solutions. This consists of smallest form factor modules, with proven software that decreases time to market and improves the end-user experience," said Moses Asom, SyChip co-founder and senior vice president of marketing and business development. "We serve as a solution provider integrating application processors, operating systems and peripheral interfaces. The HS-SDIO product announcement underscores SyChip's commitment to this strategy."

"SyChip's high-speed SDIO solution delivers enhanced performance to designers creating devices running Windows Embedded CE," said Jeff Felbeck, senior partner marketing manager, Americas at Microsoft Corp. "With this increased performance, SyChip is contributing to the connected experience powered by smart, service-oriented devices with high-speed flexibility and connectivity."

The HS-SDIO product will be commercially available in Q4 2007. Interested customers can visit <http://www.sychip.com/products.htm> for more information and pricing.

About SyChip, Inc.

SyChip, Inc. a subsidiary of Murata Manufacturing Co., Ltd. develops and markets Chip Scale Modules, Semiconductors and Software for the wireless mobile market. The company's RF modules are differentiated due to proprietary integration and low loss silicon technologies. As a result of this integration, world-class RF system design, proprietary multifunction ASICs, software and smart utilities, SyChip's RF designs drastically reduce component count, offer very small footprints and are easy to integrate into a mobile device. Customers benefit by significantly reducing their time-to-market, increasing performance and improving reliability of their wireless devices. SyChip has received multiple awards, including *Internet Telephony's* 2005 Product of the Year, Deloitte's 2005 "Fast 500", the TiEcon 2005 Emerging Star Award, MobileTrax "2005 Mobility Award", finalist for the "2005 *Red Herring* 100", Deloitte's 2004 "Fast 500 Rising Star Award" and "Best Wireless Accessory" by *Handheld Computing*.

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